
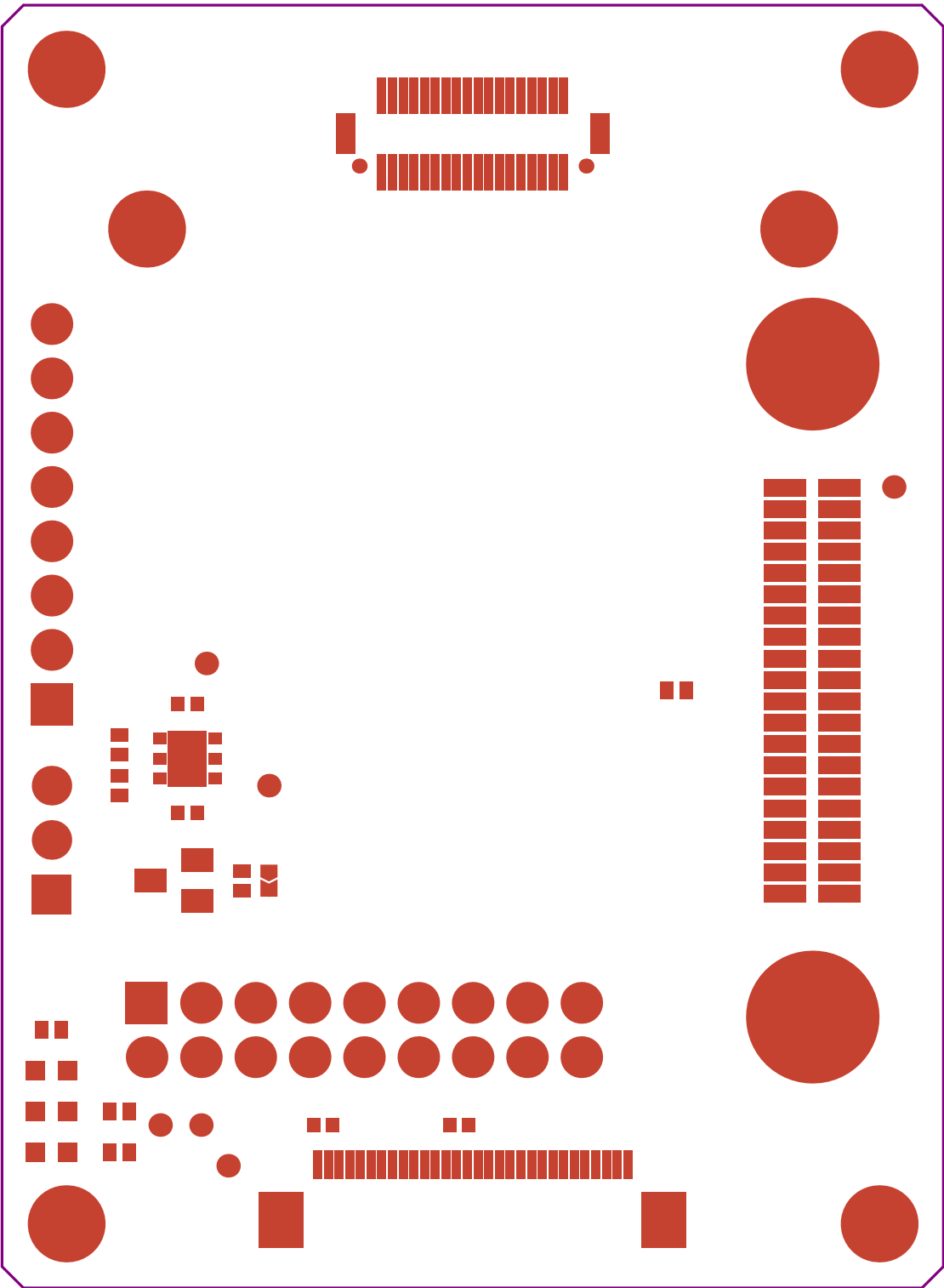

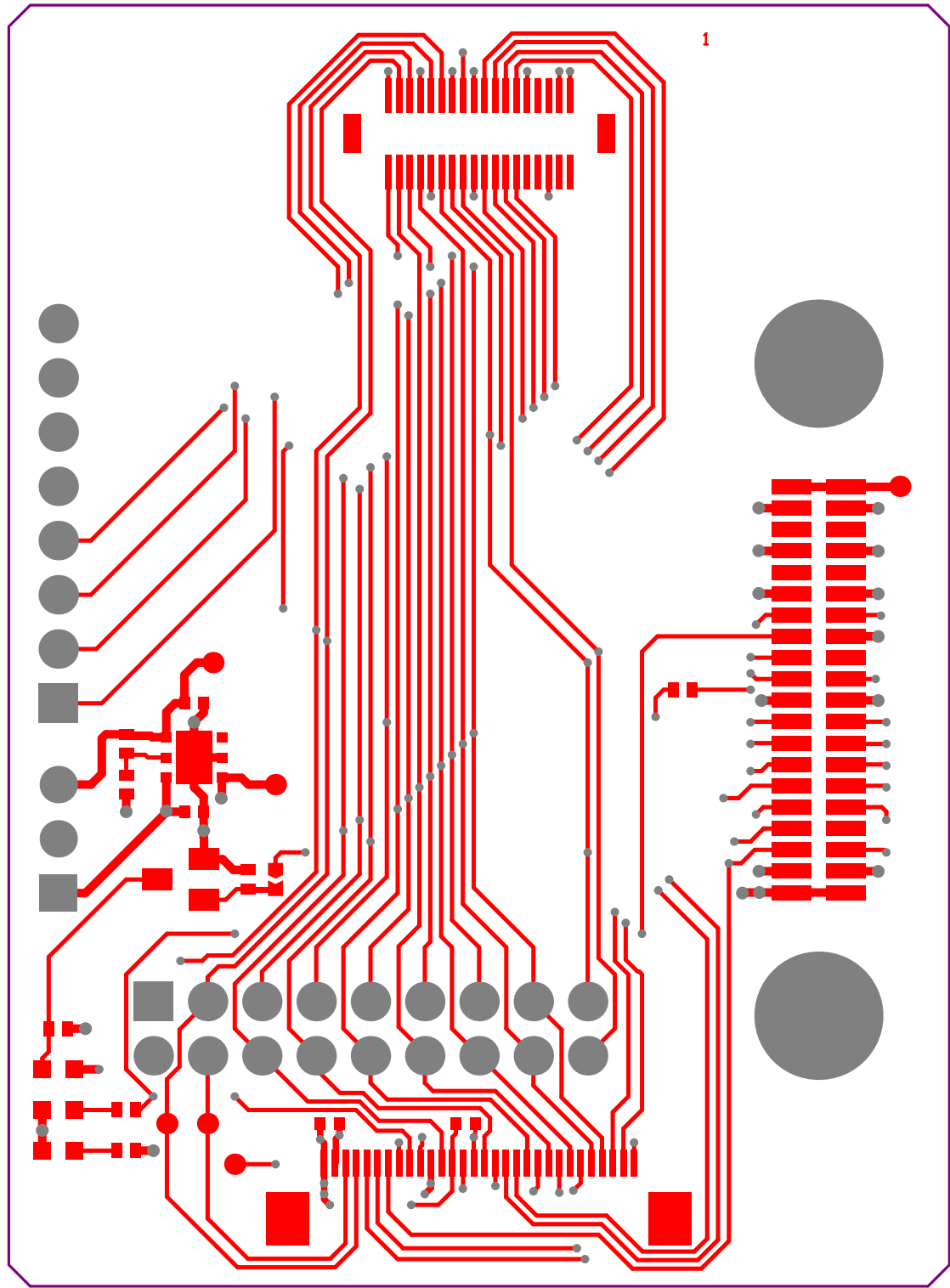



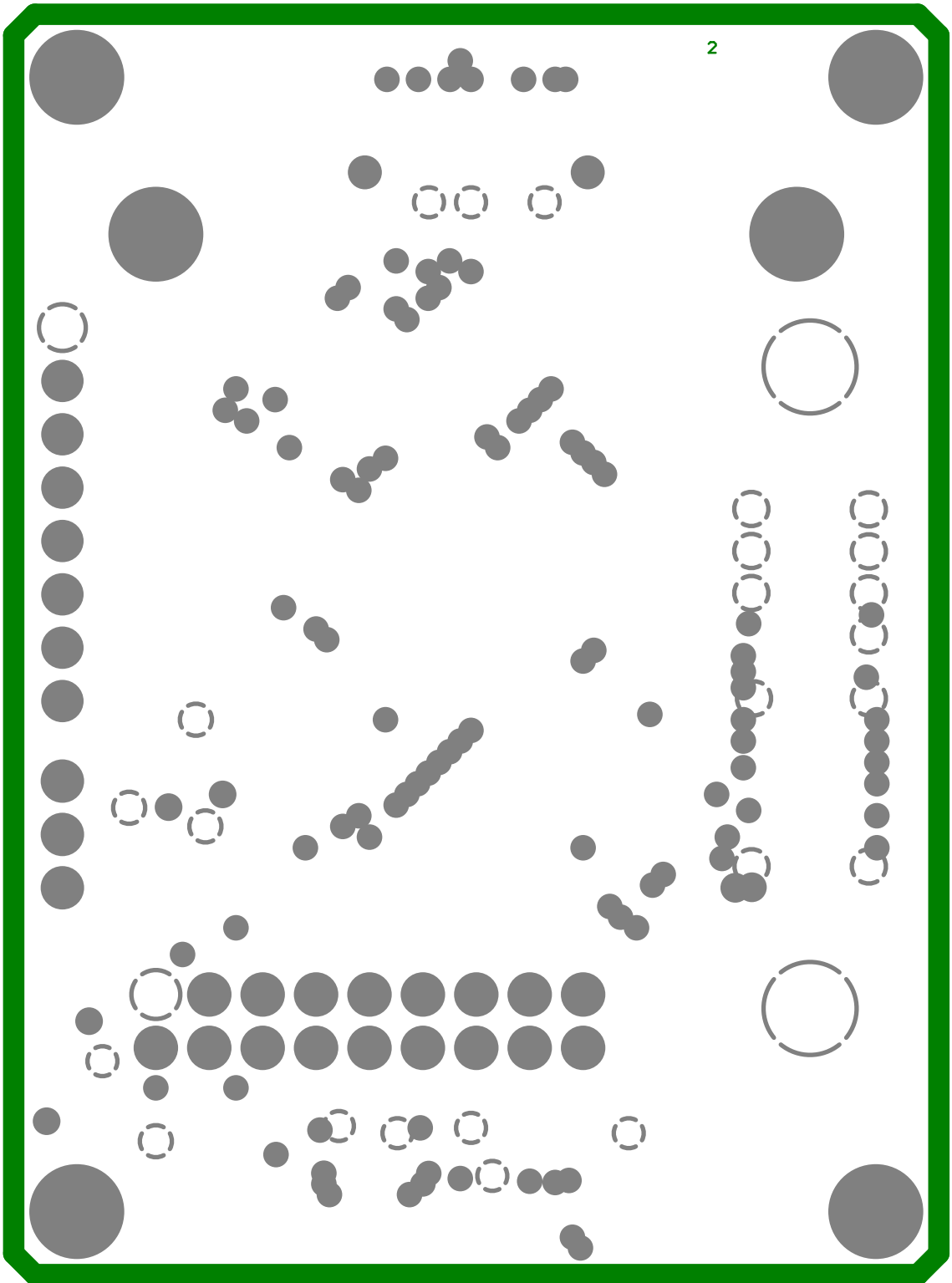
Project: Camera module Bundle		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB1683	
Date: 06-MAY-20	Rev: A	




Project: Camera module Bundle		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1683	
Date: 06-MAY-20	Rev: A	

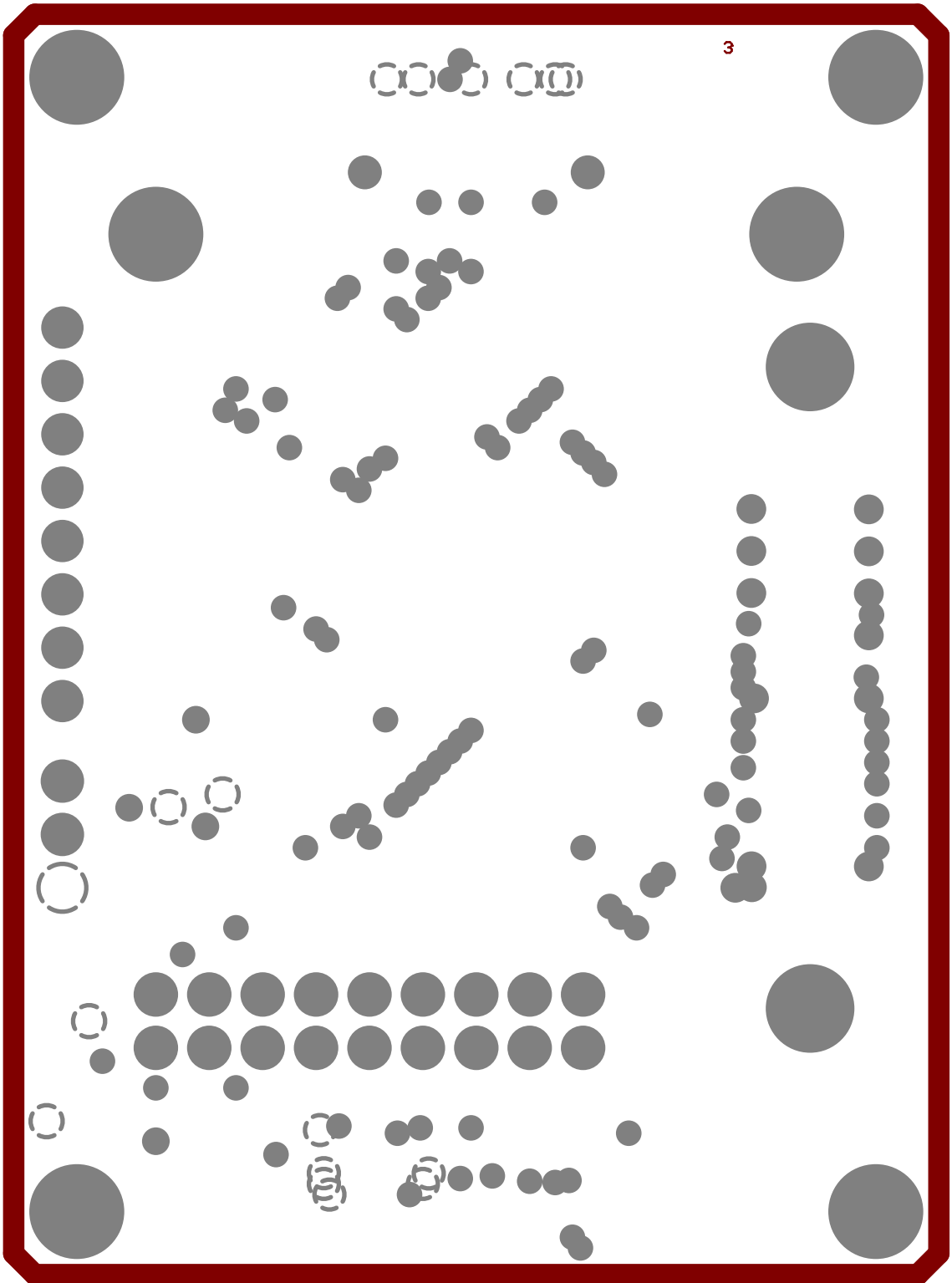



Project: Camera module Bundle		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB1683	
Date: 06-MAY-20	Rev: A	

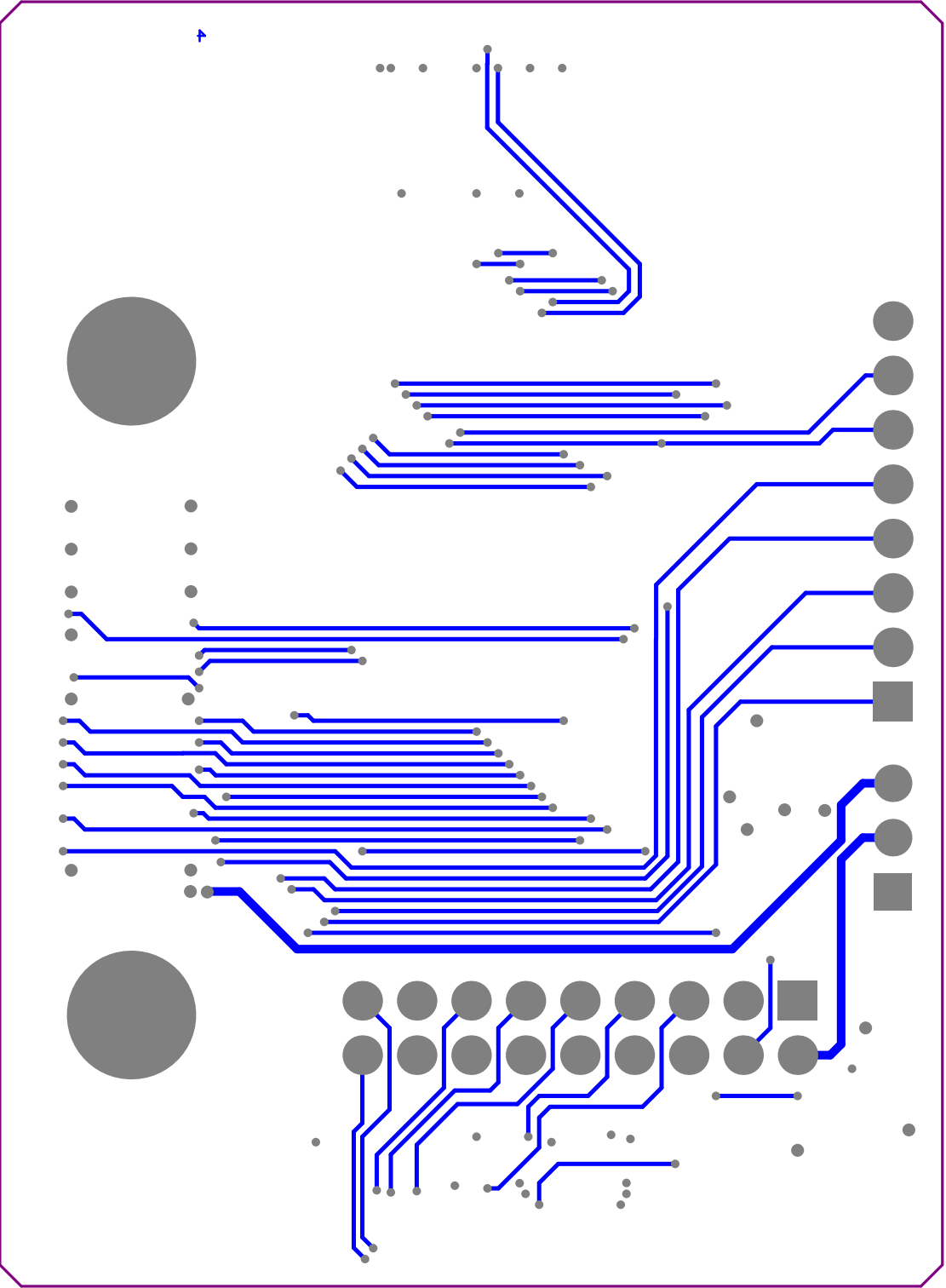



2

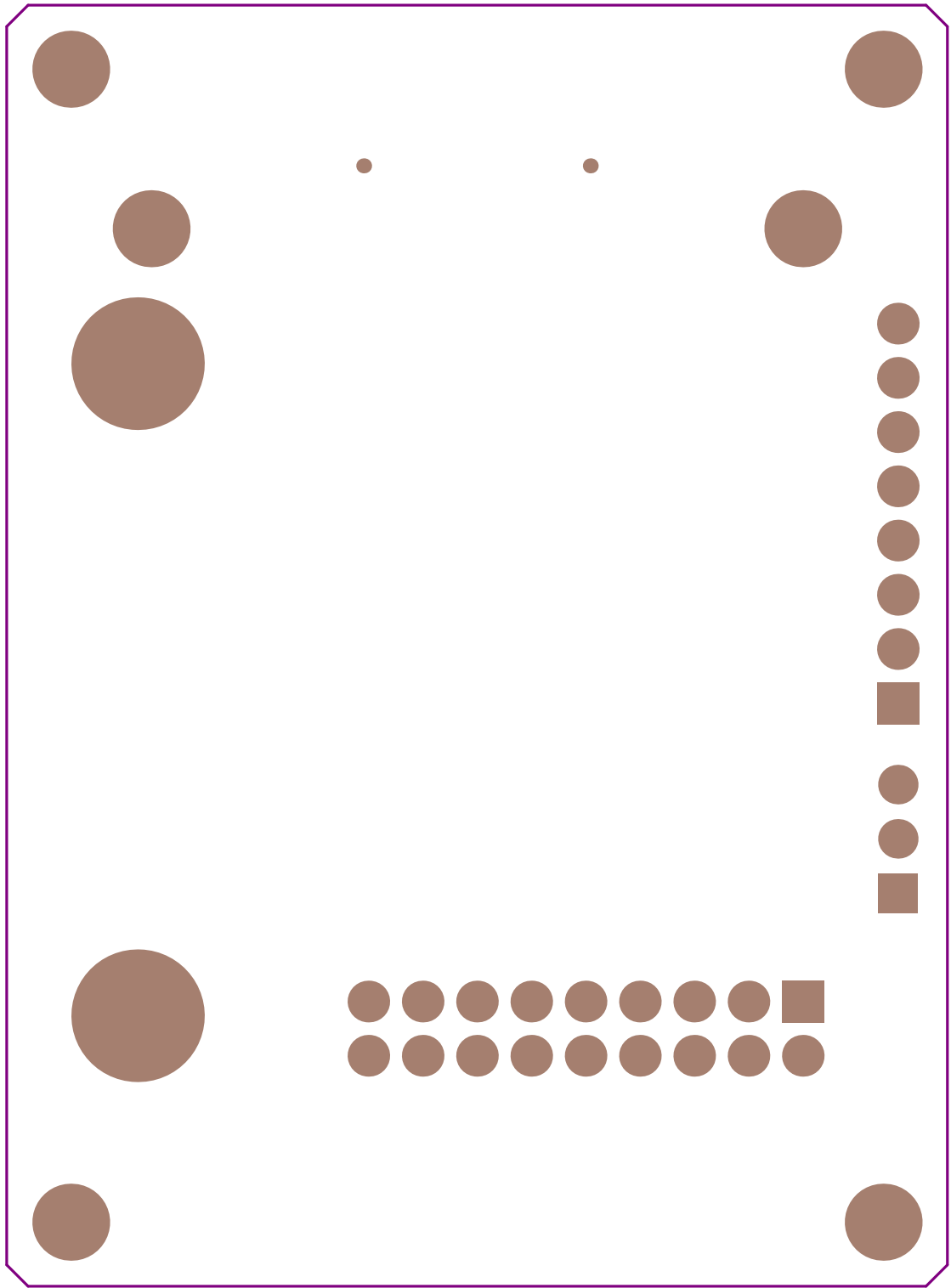
Project: Camera module Bundle		
Layer: GND	Gerber: .GP1	
Variant: [No Variations]	Ref: MB1683	
Date: 06-MAY-20	Rev: A	




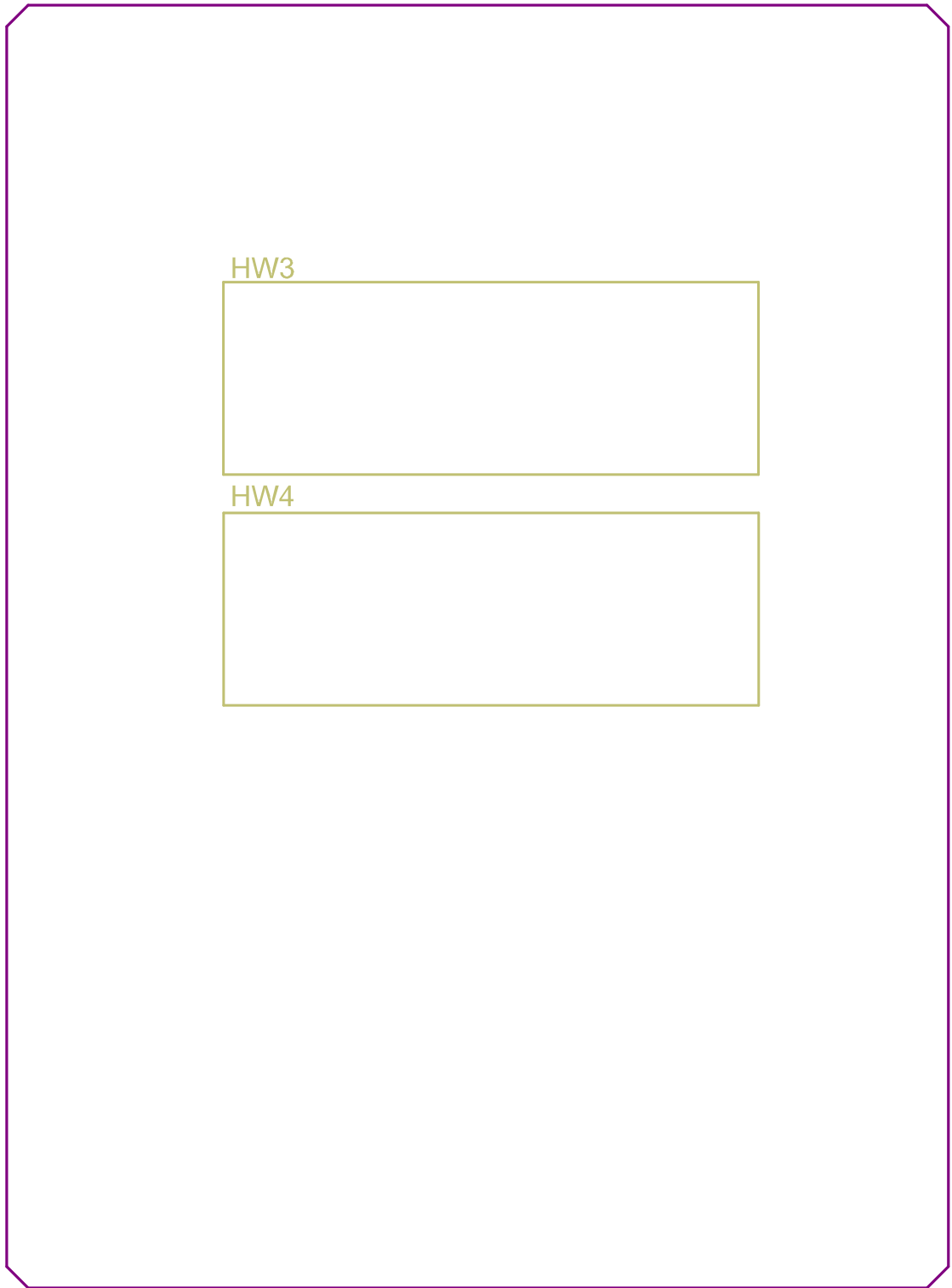
Project: Camera module Bundle		
Layer: VCC	Gerber: .GP2	
Variant: [No Variations]	Ref: MB1683	
Date: 06-MAY-20	Rev: A	




Project: Camera module Bundle		
Layer: Bottom Layer	Gerber:.GBL	
Variant: [No Variations]	Ref: MB1683	
Date: 06-MAY-20	Rev: A	



Project: Camera module Bundle		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB1683	
Date: 06-MAY-20	Rev: A	



Project: Camera module Bundle		
Layer: Bottom Overlay	Gerber:.GBO	
Variant: [No Variations]	Ref: MB1683	
Date: 06-MAY-20	Rev: A	

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

N/A

☐ GREEN

☒ WHITE

☒ ENIG

☒ HASL

☒ NO

☐ WHITE

☐ YELLOW

☐ IMMERSION SILVER

☐ HASL (PB-FREE)

☐ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

☒ TG-150

☐ TG-140

Blue ink PANTONE 2955

IMMERSION TIN

GOLDEN FINGER

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.
SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

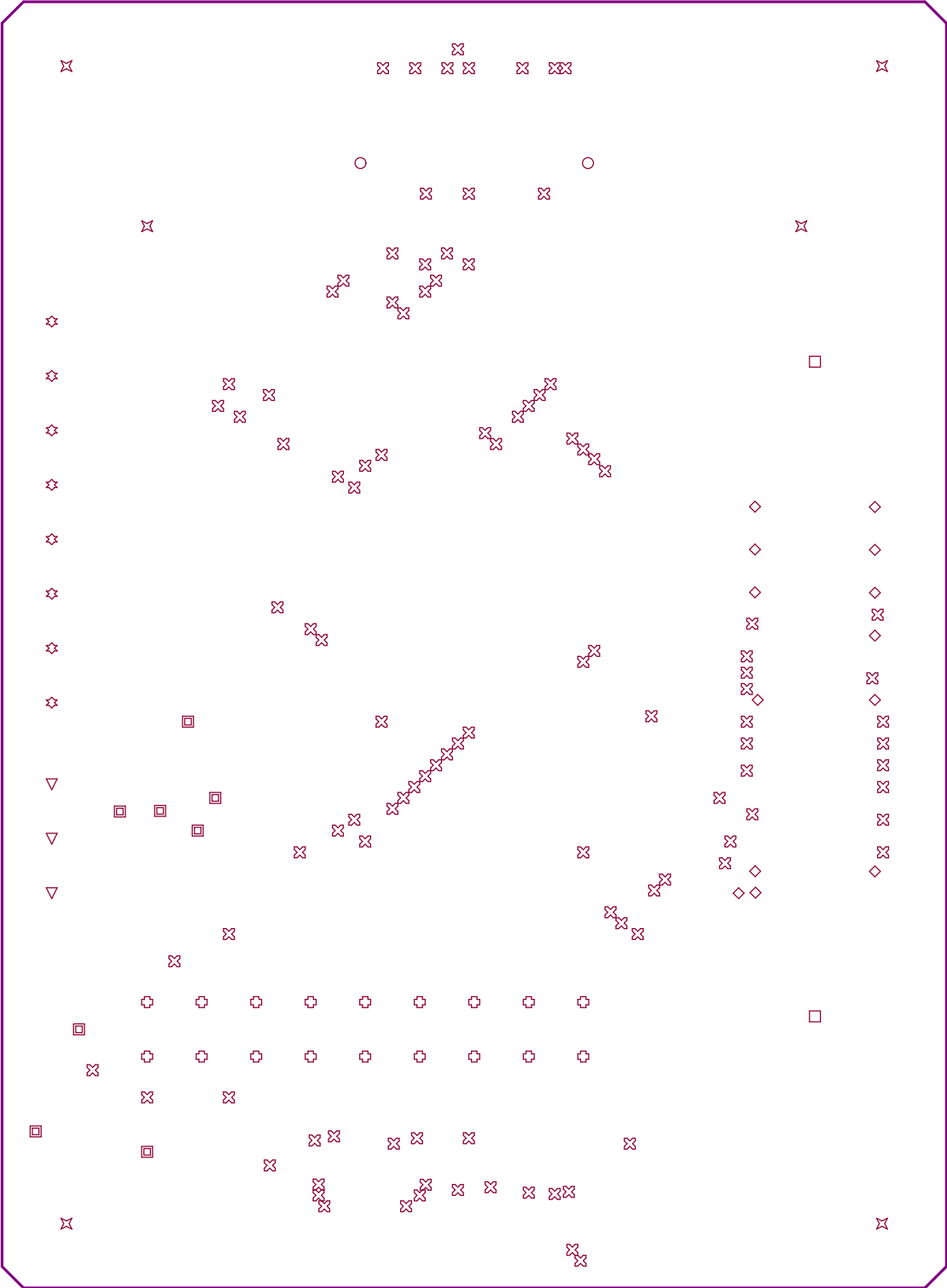
PCB : TYPE 3

ASPECT-RATIO, AXE Z :

6:1 to 8:1
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.127mm
GAPS : 0.127mm



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
⊗	109	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v40h20m0mx0
⊠	8	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v60h30m0mx0
◇	13	15.75mil (0.400mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v60h40m0mx0
○	2	23.62mil (0.600mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn60m65
☆	8	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)
▽	3	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
⊕	18	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)
□	2	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c600h320m610
⊗	6	137.80mil (3.500mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn350m355
	169 Total							

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.59mil	3.5	
3	Top Layer	Copper	1.38mil		
4	Dielectric 1	FR-4	20.00mil	4.2	
5	GND	Copper	1.42mil		
6	Dielectric 3		16.00mil	4.2	
7	VCC	Copper	1.42mil		
8	Dielectric 2		20.00mil	4.2	
9	Bottom Layer	Copper	1.38mil		
10	Bottom Solder	Solder Resist	0.59mil	3.5	
11	Bottom Overlay				

Project: Camera module Bundle

Layer: Drill Drawing

Variant: [No Variations]

Date: 06-MAY-20

Gerber: .DRL

Ref: MB1683

Rev: A

